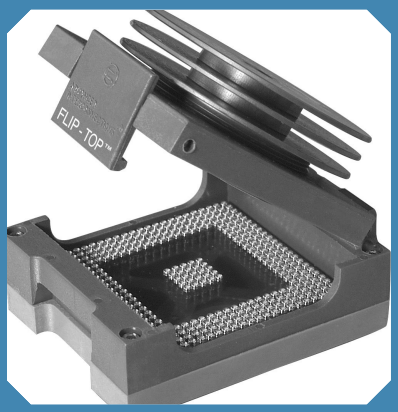
Flip-Top™ BGA Sockets



Features:

- Designed to save space on new and existing PC boards in test, development, programming and production applications.
- No external hold-downs or soldering of BGA device required.
- AIC exclusive solder ball terminals offer superior processing.
- Uses same footprint as BGA device.
- Available with integral, finned heat sink or coin screw clamp assembly.

Specifications:

Terminals:
Brass - Copper Alloy (C36000) ASTM-B-16

Contacts:
Beryllium Copper (C17200) ASTM-B-194

Plating:
G - Gold over Nickel

Terminal Support:
Polymide Film

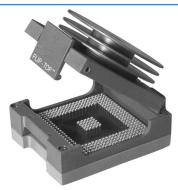
Spring Material:
Stainless Steel

Heat Sink/Coin Screw and Support Plate Material:
Aluminum

Solder Ball:
Standard: 63Sn/37Pb
Lead-free: 95.5Sn/4.0Ag/0.5Cu

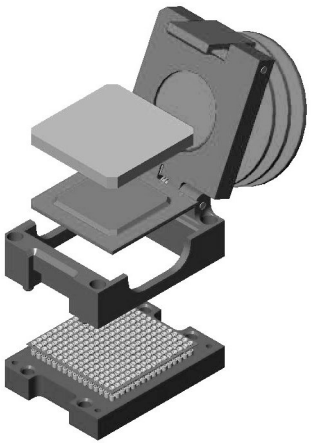
ADVANCED INTERCONNECTIONS

Table of Models

	Description: Molded Socket (FRG, 1.27mm pitch) Material: High Temp. Liquid Crystal Polymer (LCP) Index: -40°C to 260°C (-40°F to 500°F)	Socket Size: 3mm wider and 10mm longer than BGA device.
	Description: Molded Socket (FRH, 1.00mm pitch) Material: High Temp. Liquid Crystal Polymer (LCP) Index: -40°C to 260°C (-40°F to 500°F)	Socket Size: 3mm wider and 10mm longer than BGA device.

FRG replaces FTG. Consult factory for availability of FRH.

How It Works



SMT models are shipped un-assembled to ease solderability. Thru-hole models are shipped fully assembled.

1. Lower assembly is soldered to PC board with no external hold-down mechanism. Thru-hole models may be soldered to PC board or plugged into a mating socket.
2. Upper assembly inserts easily to lower assembly by aligning guide posts and installing four (supplied) screws.
3. Finned heat sink or coin screw is screwed down to flush position.
4. Lid opens easily by pressing latch.
5. BGA device is inserted by aligning A1 position with chamfered corner of Flip-Top™ socket. Place support plate on top of device, close lid, engage heat sink or coin screw, and socket is ready for use.

Detailed Installation and General Usage Instructions are provided with product.

How To Order

Pb free RoHS compliant

1 FR G XXXX - 821 G G XX

Footprint Dash #
If Applicable*

Model Type
RoHS Compliant Insulator:
FR - Flip-Top™ BGA Socket

Pitch
G = .050/(1.27mm)
H = .039/(1.00mm)

Number of Positions
*Footprints available online or in separate booklet

Terminal Type
See options

Terminal Plating
RoHS Compliant:
G - Gold

Contact Plating
RoHS Compliant:
G - Gold

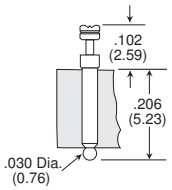
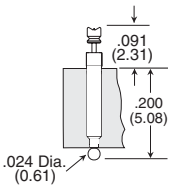
Clamp Options
HS - Heat Sink (3 Fins Std.)
CS - Coin Screw

Flip-Top™ BGA Sockets

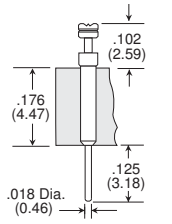
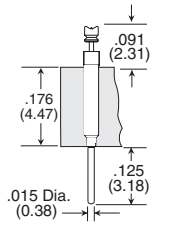
Standard Terminals

(for test, development and production applications)

SMT (Surface Mount)

Tin/Lead: Type -690 Lead-free: Type -821	Tin/Lead: Type -TBD Lead-free: Type -TBD
1.27mm pitch	1.00mm pitch
	

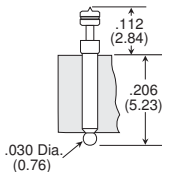
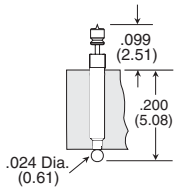
Thru-Hole

Type -708	Type -TBD
	

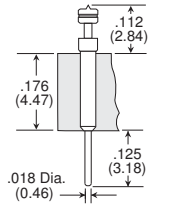
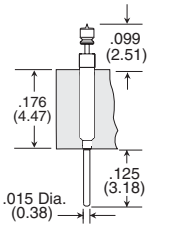
Standard Terminals

(for LGA or De-balled BGA device applications)

SMT (Surface Mount)

Tin/Lead: Type -713 Lead-free: Type -822	Tin/Lead: Type -TBD Lead-free: Type -TBD
1.27mm pitch	1.00mm pitch
	

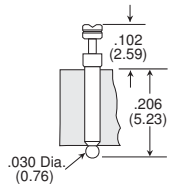
Thru-Hole

Type -712	Type -TBD
	

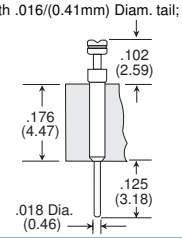
Standard Terminals

(for BGA Device Test Applications)

SMT (Surface Mount)

Tin/Lead: Type -659 Lead-free: Type -820	Tin/Lead: Type -TBD Lead-free: Type -TBD
1.27mm pitch	1.00mm pitch
	Consult Factory

Thru-Hole

Type -657	Type -TBD
Available with .016/(0.41mm) Diam. tail; Type -709 	Consult Factory

inch/(mm)

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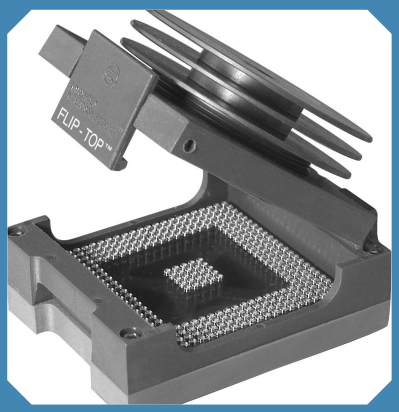
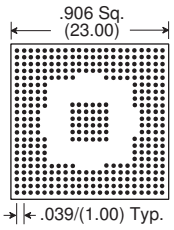


Footprints:

360 Pins
Footprint Number 360-2



22 x 22 rows

- Full grid molded insulators populated to exact device pattern
- Over 900 footprints available - search online or request BGA Footprints Booklet
- Use our Build-A-Part feature or search in our online BGA Socket Finder™ at www.bgasockets.com

Available Online:

- RoHS Qualification Test Report
- Technical articles
- Test data
- CAD drawings
- BGA Footprints

ADVANCED INTERCONNECTIONS